

FDMC7678

November 2013

N-Channel Power Trench[®] MOSFET 30 V, 19.5 A, 5.3 m Ω

Features

- Max $r_{DS(on)} = 5.3 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 17.5 \text{ A}$
- Max $r_{DS(on)}$ = 6.8 m Ω at V_{GS} = 4.5 V, I_D = 15.0 A
- High performance technology for extremely low r_{DS(on)}
- Termination is Lead-free and RoHS Compliant

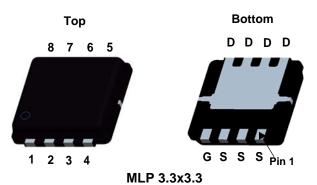
General Description

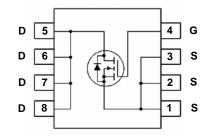
This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been especially tailored to minimize the on-state resistance. This device is well suited for Power Management and load switching applications common in Notebook Computers and Portable Battery Packs.

Application

- DC DC Buck Converters
- Notebook battery power management
- Load switch in Notebook







MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units
V_{DS}	Drain to Source Voltage		30	V	
V_{GS}	Gate to Source Voltage		(Note 3)	±20	V
I _D	Drain Current -Continuous (Package limited)	T _C = 25 °C		19.5	
	Drain Current -Continuous (Silicon limited)	T _C = 25 °C		63	^
	-Continuous	T _A = 25 °C	(Note 1a)	17.5	Α
	-Pulsed			70	
E _{AS}	Single Pulse Avalanche Energy		(Note 4)	54	mJ
D	Power Dissipation	T _C = 25 °C		31	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	2.3	VV
T _J , T _{STG}	Operating and Storage Junction Temperature Ra	ange		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	4.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a	53	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC7678	FDMC7678	MLP 3.3x3.3	13 "	12 mm	3000 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Parameter

Off Char	Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30			V	
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		21		mV/°C	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			1	μΑ	
I _{GSS}	Gate to Source Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA	

Test Conditions

Min

Тур

Max

Units

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.2	1.5	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = 250 μA, referenced to 25 °C		-5		mV/°C
r _{DS(on)} Static Drain to Source On Resistance		V _{GS} = 10 V, I _D = 17.5 A		4.2	5.3	
	Static Drain to Source On Pesistance	$V_{GS} = 4.5 \text{ V}, I_D = 15.0 \text{ A}$		5.1	6.8	mΩ
	$V_{GS} = 10 \text{ V}, I_D = 17.5 \text{ A}$ $T_J = 125 ^{\circ}\text{C}$		5.7	7.2	11122	
g _{FS}	Forward Transconductance	$V_{DD} = 5 \text{ V}, I_{D} = 17.5 \text{ A}$		90		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 45 V V 0 V	1810	2410	pF
Coss	Output Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}$ = 1MHz	620	820	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11/11/2	75	110	pF
R_q	Gate Resistance		0.7	2.5	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		10	19	ns
t _r	Rise Time	V _{DD} = 15 V, I _D = 17.5 A	4	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	26	41	ns
t _f	Fall Time		3	10	ns
0	Total Gate Charge	V _{GS} = 0 V to 10 V	28	39	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 15 \text{ V}$	14	19	nC
Q_{gs}	Gate to Source Charge	I _D = 17.5 A	4.4		nC
Q _{gd}	Gate to Drain "Miller" Charge		3.9		nC

Drain-Source Diode Characteristics

V _{SD} Source	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 1.9 \text{ A}$ (Note 2)	0.7	1.2	W
	Source to Drain blode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 17.5 \text{ A}$ (Note 2)	0.8	1.2	, v
t _{rr}	Reverse Recovery Time	I _E = 17.5 A, di/dt = 100 A/μs		49	ns
Q _{rr}	Reverse Recovery Charge	$-1_F = 17.5 \text{ A}, \text{ di/dt} = 100 \text{ A/} \mu\text{S}$	13	23	nC

NOTES

^{1.} R_{0,1A} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,1C} is guaranteed by design while R_{0,1C} is determined by the user's board design.



a. 53 °C/W when mounted on a 1 in² pad of 2 oz copper



b.125 °C/W when mounted on a minimum pad of 2 oz copper

- 2. Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0 %.
- 3. As an N-ch device, the negative V_{GS} rating is for low duty cycle pulse occurrence only. No continuous rating is implied.
- 4. E_{AS} of 54 mJ is based on starting T_J = 25 o C, L = 0.3 mH, I_{AS} = 19 A, V_{DD} = 27 V, V_{GS} = 10 V.

Typical Characteristics T_J = 25°C unless otherwise noted

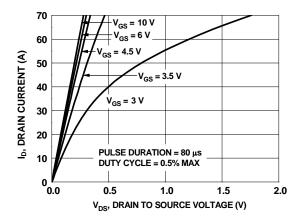


Figure 1. On Region Characteristics

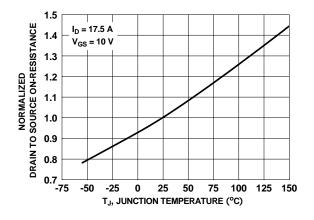


Figure 3. Normalized On Resistance vs Junction Temperature

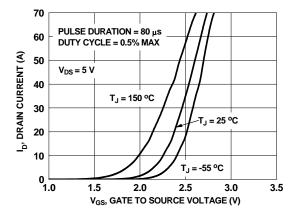


Figure 5. Transfer Characteristics

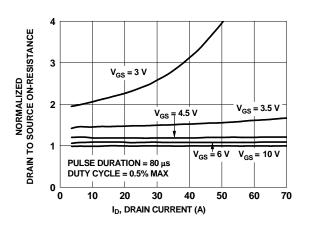


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

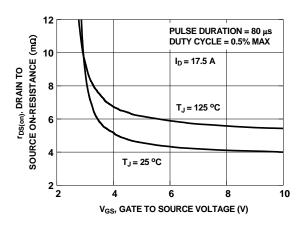


Figure 4. On-Resistance vs Gate to Source Voltage

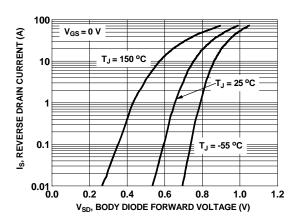


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

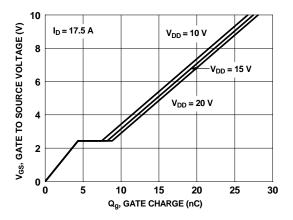


Figure 7. Gate Charge Characteristics

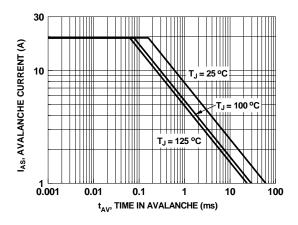


Figure 9. Unclamped Inductive Switching Capability

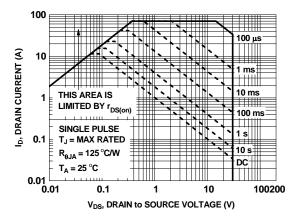


Figure 11. Forward Bias Safe Operating Area

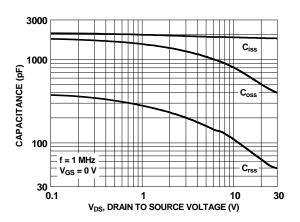


Figure 8. Capacitance vs Drain to Source Voltage

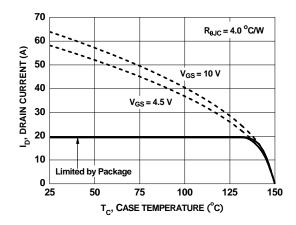


Figure 10. Maximum Continuous Drain Current vs Case Temperature

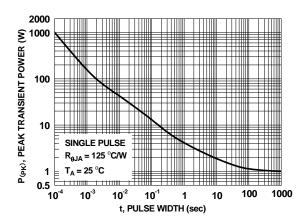


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25°C unless otherwise noted

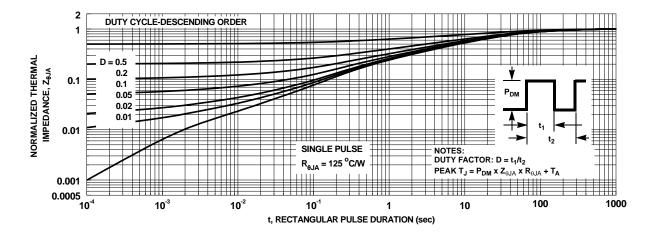
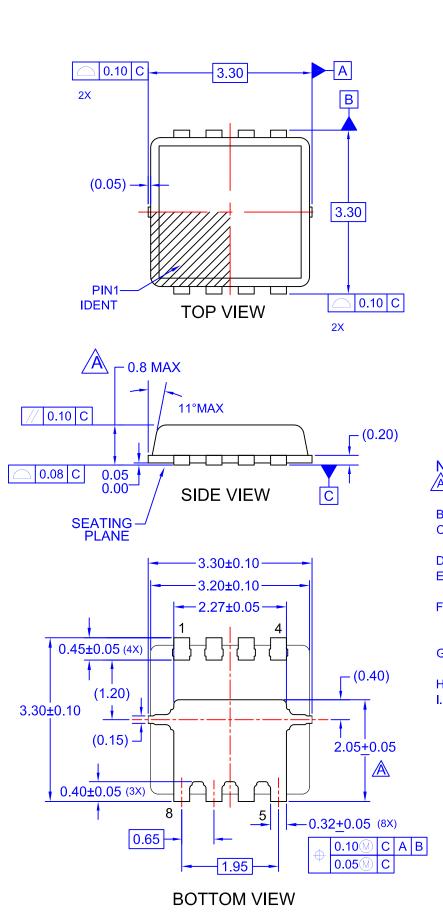
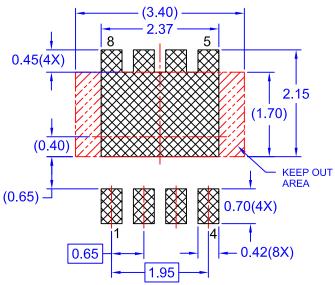


Figure 13. Junction-to-Ambient Transient Thermal Response Curve





RECOMMENDED LAND PATTERN

NOTES:

- EXCEPT AS NOTED, PACKAGE CONFORMS TO JEDEC REGISTRATION MO-240 VARIATION BA.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. SEATING PLANE IS DEFINED BY TERMINAL TIPS ONLY
- E. BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH PROTRUSIONS NOR GATE BURRS.
- F. FLANGE DIMENSIONS INCLUDE INTERTERMINAL FLASH OR PROTRUSION. INTERTERMINAL FLASH OR PROTRUSION SHALL NOT EXCEED 0.25MM PER SIDE.
- G. IT IS RECOMMENDED TO HAVE NO TRACES OR VIA WITHIN THE KEEP OUT AREA.
- H. DRAWING FILENAME: MKT-MLP08Trev4.
- GENERAL RADII FOR ALL CORNERS SHALL BE 0.20MM MAX.







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Definition of Terms

Definition of Terms					
Datasheet Identification	Product Status	Definition			
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.			
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.			
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